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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/741,321	12/18/2003	How-Cheng Tsai	N1085-00164	4502
54657 7	590 08/19/2005		EXAM	INER
DUANE MO			DEO, DUY VU NGUYEN	
IP DEPARTMENT (TSMC) 4200 ONE LIBERTY PLACE		•	ART UNIT	PAPER NUMBER
PHILADELPHIA, PA 19103-7396			1765	

DATE MAILED: 08/19/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		r V				
	Application No.	Applicant(s)				
	10/741,321	TSAI ET AL.				
Office Action Summary	Examiner	Art Unit				
	DuyVu n. Deo	1765				
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet with the	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a report of the period for reply is specified above, the maximum statutory period for reply within the set or extended period for reply will, by statuted the period for reply will be period for reply will		timely filed ays will be considered timely. m the mailing date of this communication. NED (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 16 L	December 2004.					
2a) This action is FINAL . 2b) ☑ Thi	_ ·					
,	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims	•					
4) ☐ Claim(s) 1-19 is/are pending in the application 4a) Of the above claim(s) is/are withdra 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-9 and 12-19 is/are rejected. 7) ☐ Claim(s) 10 and 11 is/are objected to. 8) ☐ Claim(s) are subject to restriction and/	awn from consideration.					
Application Papers	•					
9)☐ The specification is objected to by the Examin	er.					
,	cepted or b) objected to by the					
Applicant may not request that any objection to the	- · ·					
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the E						
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreig a) All b) Some * c) None of: 1. Certified copies of the priority documer 2. Certified copies of the priority documer 3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a lis	nts have been received. Its have been received in Applica Ority documents have been recei au (PCT Rule 17.2(a)).	ation No ved in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date 12/18/03. S. Patent and Trademark Office	4) Interview Summa Paper No(s)/Mail 5) Notice of Informal 6) Other:					

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1-3, 7, 12, 13, 17 are rejected under 35 U.S.C. 102(b) as being anticipated by Shan et al. (US 5,514,247).

Shan describes an etching method of via comprising: exposing the underlying Al layer (claimed Al-containing bond pad) to an overetch RIE gases comprises of CF4, Cl2, BCl3 (claimed chemical etching gases) and Ar (claimed physical etching); applying the energy to the gas mixture to form a plasma inside the RIE system (col. 3, line 5-15, 35-37; col. 4, line 16-65). Even though Shan is silent about the active plasma removes the fluorine contaminants, such as AlFO oxide from the Al layer by physical and chemical etching; however, he teaches using of the same gases, and therefore, the gas mixture would also remove the fluorine contaminants from the Al layer.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 8, 9, 18, 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shan.

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Shan further describes the pressure in the chamber is 50-300 mtorr, the power is 300-800 watts. He doesn't describe the time for the overetch such as at least 60 seconds or about 120 seconds. However, it would have been obvious for one skilled in the art to determine the overetch time through routine experimentation in order to provide the optimum time for removing the contaminants and residues with a reasonable expectation of success.

5. Claims 4-6, 14-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shan as applied to claims 1, 13 above, and further in view of Chen et al. (US 6,692,903).

Unlike claimed invention, Shan doesn't describe the gas mixture having SF6. He shows the Ar and CF4 flow rates are 10-150 sccm and 0-50 sccm respectively. Chen teaches an etching method where fluorine gas including SF6 is added for cleaning residues (col. 11, line 1-7, 44-51). It would have been obvious for one skilled in the art to modify Shan in light of Chen's teaching using of SF6 because Chen teaches that it would effectively remove and/or soften polymer resist and residue on the substrate and also clean the residue from the substrate and chamber (col. 11, line 1-7, 44-51).

Allowable Subject Matter

6. Claims 10 and 11 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Claims 10 and 11 are allowable because applied prior art doesn't suggest or provide motivation for applying a step of a low energy O2 plasma etching for partially removing polyimide passivation layer from the wafer to remove any fluorine-based residue or a high

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energy O2 plasma etching for completely removing polyimide passivation layer from the wafer to remove any chlorine-based residue.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DuyVu n. Deo whose telephone number is 571-272-1462. The examiner can normally be reached on 6:00-2:30 Mon-Fri.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Primary Examiner Duy-Vu N. Deo

8/8/05